



NEWS: FOR IMMEDIATE RELEASE

**Microbonds, Mirror Semiconductor and
PROMEX Industries Announce Major Packaging Technology Alliance**

(July 31, 2007)-- Microbonds Inc., Ontario, Canada; Mirror Semiconductor Inc., Irvine, Calif.; and PROMEX Industries Inc., Santa Clara, Calif., will blend their existing processes, products and expertise to develop advanced integrated circuit (IC) packaging.

This collaborative engineering effort will enable Promex (www.promex-ind.com), a leader in preparing new technologies for transfer to high-volume environments, to use Microbond's "X-Wire" technology and to co-develop IC package types which use Mirror Semiconductor's novel *Mirrored Pinout*™ designs.

X-Wire Technology (www.microbonds.com) allows interconnect bonding wires to touch and cross without electrical shorting, permitting fuller utilization of the *x,y* and *z* dimensions in electronics design and packaging.

Both Mirror Semiconductor (www.mirrorsemi.com) and Microbonds provide new packaging technologies designed to extend the life cycle and technical capabilities of today's packaging infrastructures with the lowest cost solution.

Mirror Semiconductor's *Chip Packaging 2.0* products and services enable package designers to create optimum circuit boards with shorter copper tracings and fewer layers at the lowest cost with reduced time-to-market.

Today's IC designs and board designs are pushing the limits of current technologies as the industry continues to decrease geometries and costs while increasing functionality and interconnect densities.

Providing package and board designers with the flexibility to solve these issues effectively, other than through the typical approach of increasing layers with their corresponding additional costs, requires collaborative development between adjacent processes and technologies.

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Richard Otte, CEO of Promex, said, “We are delighted to work with Microbonds and Mirror Semiconductor on this initiative. Our experience has taught us that the introduction of new materials and processes is much easier and faster when the parties can work openly together to achieve the goals of end customers.”

“Promex’s proven ability to scale and transfer new technologies to volume production provides Mirror Semiconductor and our customers with the capabilities to take best advantage of our unique designs at the right combination of time and cost. X-Wire provides us with the flexibility to achieve complex package layouts with confidence”, said Martin Hart, CEO of Mirror Semiconductor.

“This collaborative effort follows our approach of bringing X-Wire to market in a way that minimizes the time, cost and risk of adoption,” said John Scott, Microbonds’ CEO.

“We have been fortunate to build a number of technology and business alliances designed to provide wins for all involved, and this relationship provides companies interested in X-Wire with the ability to have packages built, tested and prepared for volume assembly with Promex or their packager of choice.”

Scott added, “Mirror Semiconductor’s innovative technology of *Mirrored Pinout* products demonstrates the capabilities of insulated bonding wire to enable reverse wire bonding with crossing wires to make the *Mirrored Pinout* packages without the risk of shorting. We are very pleased to have the opportunity to work with Mirror Semiconductor to advance its products and services.”

Group photo caption: **Martin Hart, president of Mirror Semiconductor, displays a Mirror Semiconductor QFN package prototype that features Microbonds’ X-Wire technology, while John Scott, Microbonds’ president and CEO, looks on. At left is Richard Otte, president and CEO of PROMEX Industries, which produced the prototype.**

Package photo caption: **The Microbonds X-Wires are visible in this Mirror Semiconductor open-cavity QFN package prototype.**

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About Microbonds

Microbonds Inc. is the leading developer and licensor of insulated wire bonding technologies for use in the design and assembly of microelectronic devices. Our web address is www.microbonds.com.

About Mirror Semiconductor

Mirror Semiconductor is a start-up company providing a host of solutions in the new *Chip Packaging 2.0* environment. Its mission is to provide board designers with the ability to optimize their board designs with user-definable pinout IC packaging. New IC packaging includes, *AnyChip*,[™] *MirrorChip*[™] and *StackChip*[™] packages. Our web address is www.mirrorsemi.com.

About Promex

PROMEX Industries is a unique materials-centric packaging foundry and IC packaging assembly service provider. Molded plastic, ceramic and custom packaging solutions including SiPs, MEMS, MOEMS, MCMs, and LGAs are provided utilizing broad technical capabilities and RoHS expertise. Scalable capacity allows customer prototyping, “fast tracked” new product introductions and beta manufacturing through volume production. Our web address is www.promex-ind.com.

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